What is claimed is:

1. A sub-assembly comprising an electronic module having a generally planar surface and an interposer having a generally planar surface against which said electronic module is clamped, the improvement comprising limit means to restrict the relative movement of said module with respect to said interposer when said sub-assembly is subject to shock and/or vibration.

2. The sub-assembly according to claim 1 wherein the limit means serves to limit relative sliding movement along the x and y axis parallel to the planar surfaces.

3. The sub-assembly according to claim 1 wherein the limit means comprises restraints on two contiguous sides of the interposer.

4. The sub-assembly according to claim 1 wherein the limit means serves to limit the relative movement along the z-axis orthogonal to the planar surfaces of the module and the interposer.

5. The sub-assembly according to claim 4 wherein the limit means comprises at least two stops that serve to limit rocking movement of the module with respect to the interposer due to lack of planarity of the two mating surfaces.

6. The sub-assembly according to claim 1 wherein the module is composed of a rigid material selected from the group consisting of ceramics, dielectrics and plastic.

6. The sub-assembly according to claim 1 wherein the module is composed of a rigid material selected from the group consisting of ceramics, dielectrics and plastic.

7. The sub-assembly according to claim 1 wherein the module has 4 sides.

8. The sub-assembly according to claim 7 wherein the limit means comprises raised edges extending at right angles to the generally planar surface of the interposer, said raised edges surrounding the 4 sides of the module.

9. The sub-assembly according to claim 8 wherein the interposer has 2 contiguous edges having edge restraints positioned to contact 2 sides of the module and the other two edges are interconnected to the two other sides of the module.

10. The sub-assembly according to claim 9 wherein the interposer further includes two spaced-apart stops projecting from the interposer toward the surface of the module, the combined height of the stops being at least equal to the maximum rocking movement caused by said lack of planarity of the module.

11. The sub-assembly according to claim 10 wherein the two stops extend at right angles to the planar surface of the interposer and along two edges thereof into contact with the module.

12. A sub-assembly comprising an electronic module, said module containing a generally planar surface defined by a perimeter, said surface having small irregularities that contribute to a lack of planarity, the module clamped to interposer member, said interposer member including two spacedly positioned stops projecting toward said module, such that the combined height of the stops is at least equal to the maximum expected rocking movement of the planar surface due to the irregularities, whereby the stops engage the generally planar surface of the module.

13. The sub-assembly according to claim 12 wherein the two stops extend at right angles to the planar surface of the interposer and along two edges thereof, into contact with the module.

14. The sub-assembly according to claim 13 further wherein the module has 4 sides, and the interposer member contains means for controlling the sliding motion of said module relative to said interposer member, said means comprising a rectangular housing having two contiguous edges containing restraints positioned to contact two sides of the module and springs connecting the other two contiguous edges of the interposer member to the other two sides to the module.

15. The sub-assembly according to claim 14 wherein the planar surface of the module contains a plurality of contact sites that are aligned by the interposer member with corresponding contact pads on a printed circuit board during subsequent assembly.

16. An electronic module adapted to be electrically interconnected to a printed circuit board, through one or more contact sites on a surface of said electronic module with contact pads on a surface of the printed circuit board, said module containing a convex surface, an interposer between said printed circuit board and the convex surface of said module, said interposer including a compressible electrically conductive spring element for each contact pad and its corresponding contact site, and further including two spacedly positioned stops projecting from the interposer toward said module, such that the combined height of the stops is at least equal to the maximum expected curvature of the convex surface, whereby the stops engage the perimeter of the module.

17. The electronic module according to claim 16 wherein two stops extend at right angles to the planar surface of the interposer and along two edges thereof, into contact with the module.

18. The electronic module according to claim16 further wherein the interposer contains means for controlling the sliding motion of said module relative to said interposer, said means comprising a rectangular housing having two contiguous edges containing restraints positioned to align the contact sites of the module with the contact pads of the printed circuit board, and springs connecting the other two contiguous edges of the interposer to the other two edges to the module.